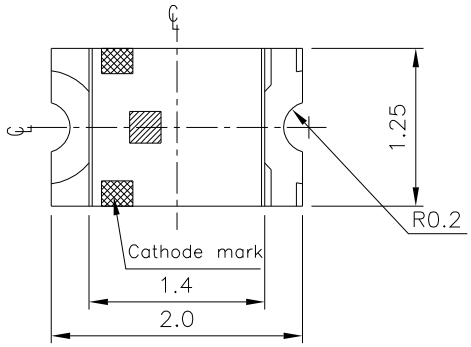
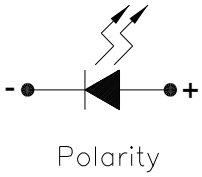
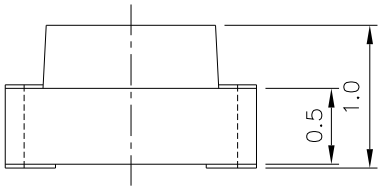
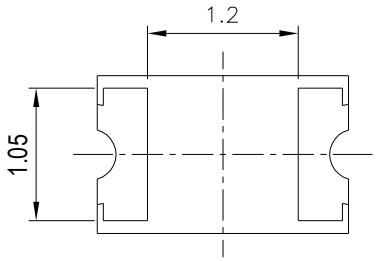
Package Outline Dimensions

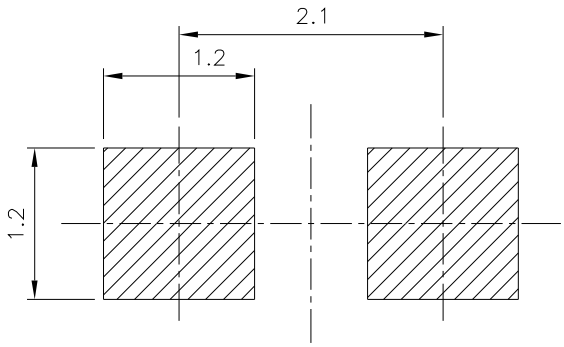






For reflow soldering (Propose)





Note: The tolerances unless mentioned is ±0.1mm ,Unit = mm

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	25	mA
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	100	mA
Power Dissipation	P_d	95	mW
ElectrostaticDischarge (HBM)	ESD	150	V
Operating Temperature	Topr	-40 ~ +85	℃
Storage Temperature	Tstg	-40 ~ +90	℃
Soldering Temperature	Tsol	Reflow Soldering: 260 ℃ for 10 sec Hand Soldering: 350℃ for 3 sec	

Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I_v	225	-----	450	mcd	I_F=20mA
Viewing Angle	$2\theta_{1/2}$	----	140	----	deg	
Peak Wavelength	λ_p	----	518	----	nm	
Dominant Wavelength	λ_d	515	----	530	nm	
Spectrum Radiation Bandwidth	$\triangle\lambda$	----	35	----	nm	
Forward Voltage	V_F	2.75	----	3.95	V	
Reverse Current	I_R	----	----	50	μA	V_R=5V

Notes:

1.Tolerance of Luminous Intensity ±11%

2.Tolerance of Dominant Wavelength ±1nm

3.Tolerance of Forward Voltage ±0.1V

Bin Range Of Dom. Wavelength

Groups	Bin	Min	Max	Unit	Condition
X	W	515	520	nm	I_F=20mA
	X	520	525		
	Y	525	530		

Bin Range Of Luminous Intensity

Bin	Min	Max	Unit	Condition
S2	225	285	mcd	I_F=20mA
T1	285	360		
T2	360	450		

Bin Range Of Forward Voltage

Groups	Bin	Min	Max	Unit	Condition
M	5	2.75	3.05	V	I_F=20mA
	6	3.05	3.35		
	7	3.35	3.65		
	8	3.65	3.95		

Notes:

1.Tolerance of Luminous Intensity ±11%

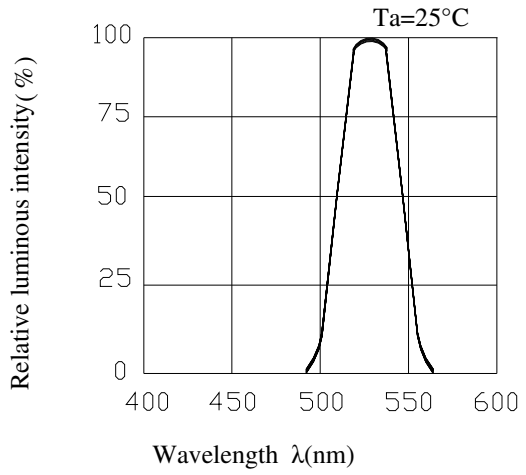
2.Tolerance of Dominant Wavelength ±1nm

3.Tolerance of Forward Voltage ±0.1V

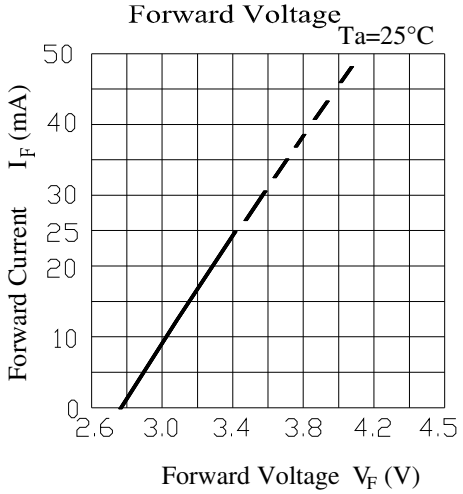
17-21/GHC-XS2T2M/3T

Typical Electro-Optical Characteri

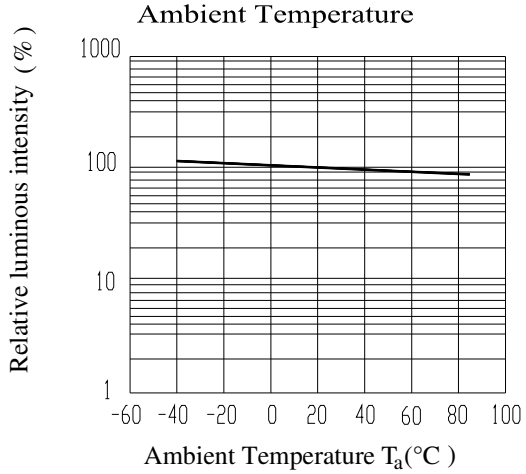
Spectrum Distribution



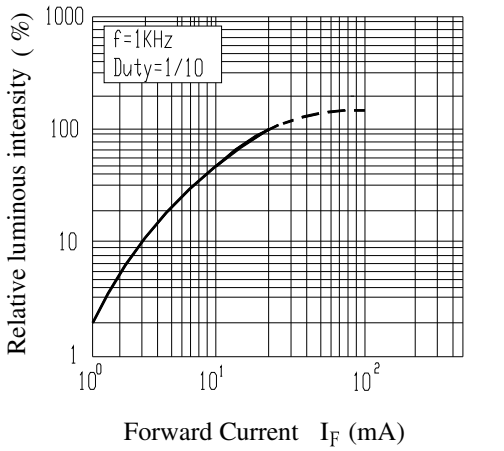
Forward Current vs. Forward Voltage



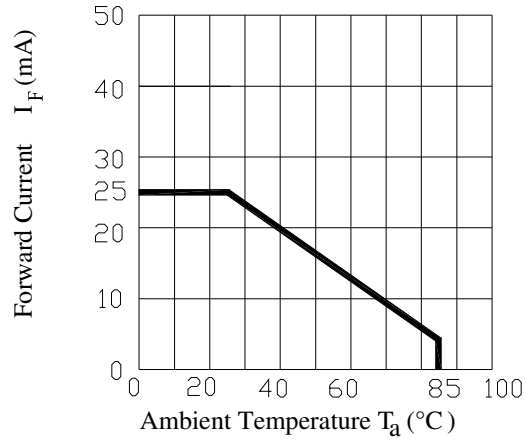
Luminous Intensity vs. Ambient Temperature



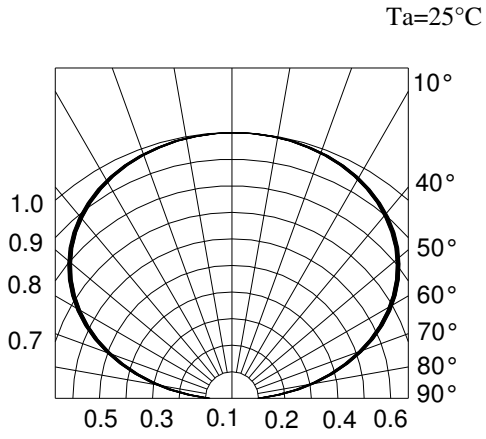
Luminous Intensity vs Forward Current



Forward Current Derating Curve



Radiation Diagram



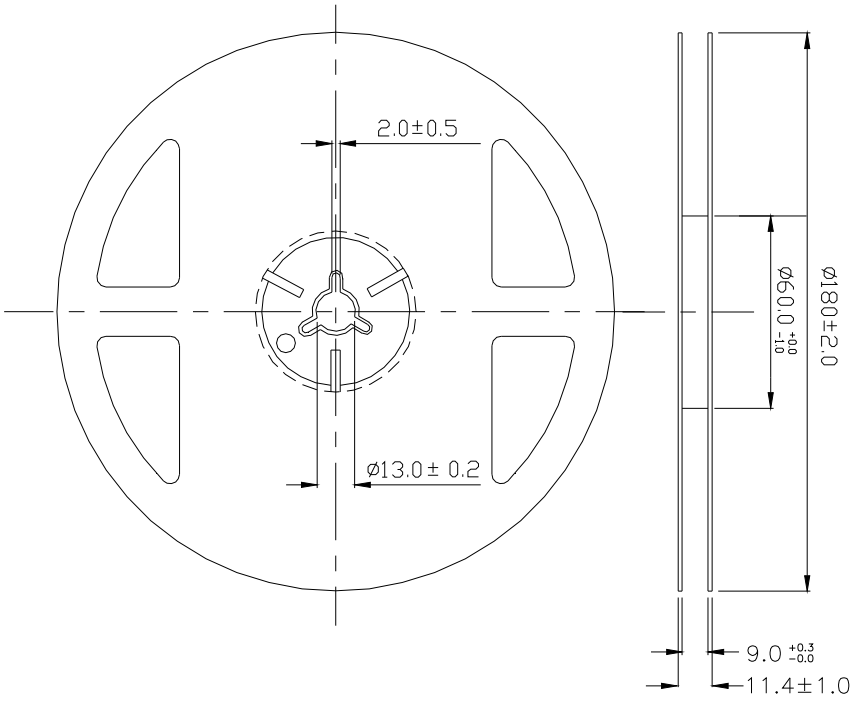
Label explanation

CAT: Luminous Intensity (mcd)

HUE: Dom. Wavelength (nm)

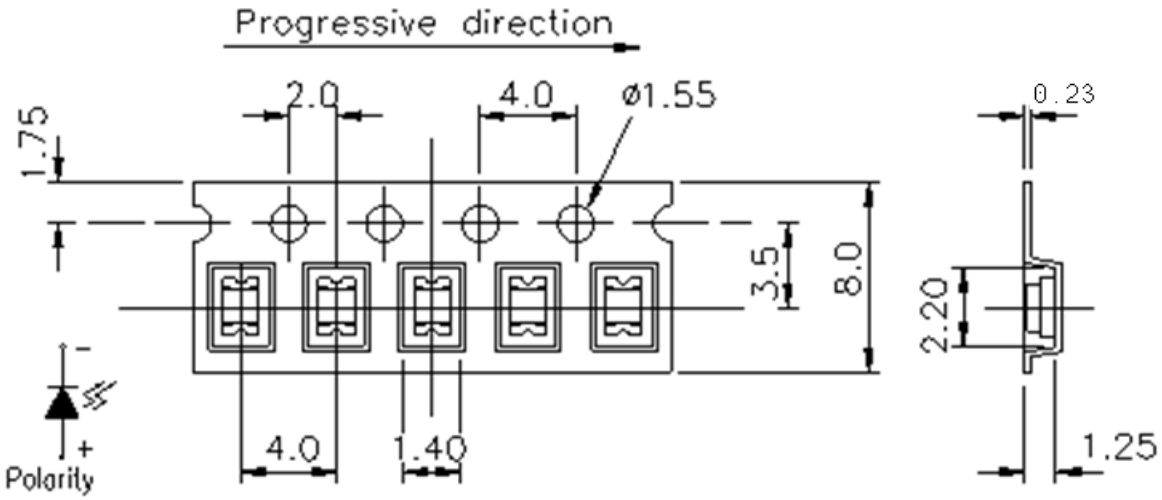
REF: Forward Voltage (V)

Reel Dimensions



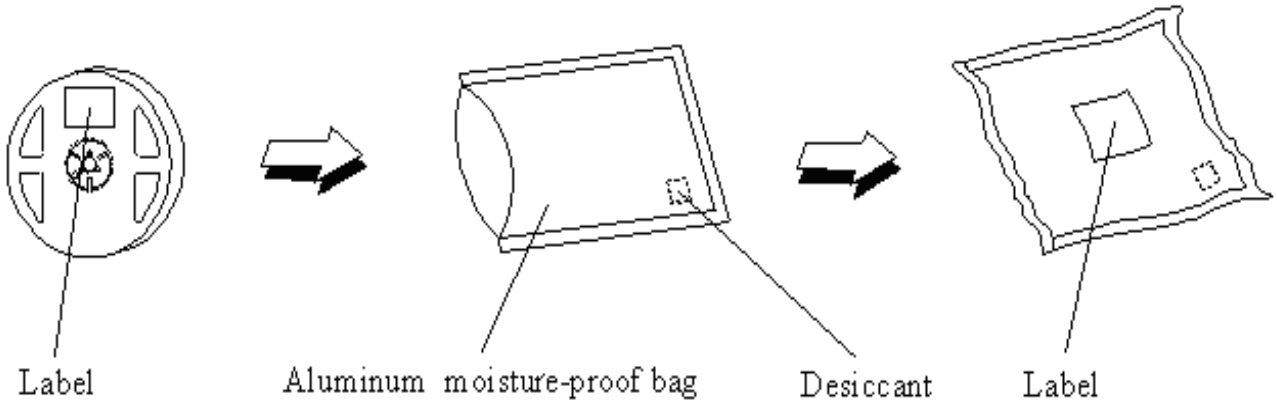
Note: The tolerances unless mentioned is ±0.1mm,Unit = mm

Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel



Note: The tolerances unless mentioned is ±0.1mm , Unit = mm

Moisture Resistant Packaging



Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.
Confidence level : 90 %
LTPD : 10 %

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260℃±5℃ Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100℃ 15min ∫ 5 min L : -40℃ 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100℃ 5min ∫ 10 sec L : -10℃ 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100℃	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40℃	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	I_F = 20 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85℃/ 85%RH	1000 Hrs.	22 PCS.	0/1

Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage time

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30℃ or less and 90%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30℃ or less and 60% RH or less.

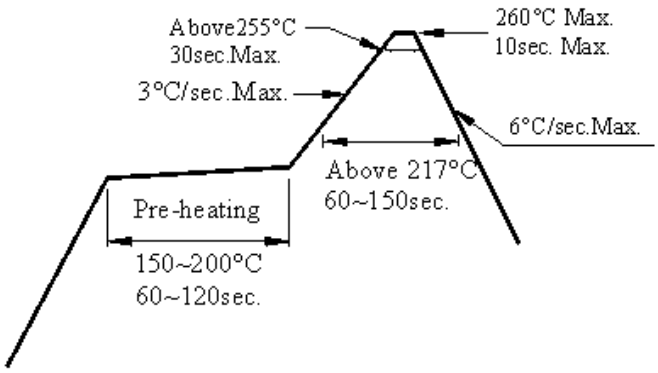
If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5℃ for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

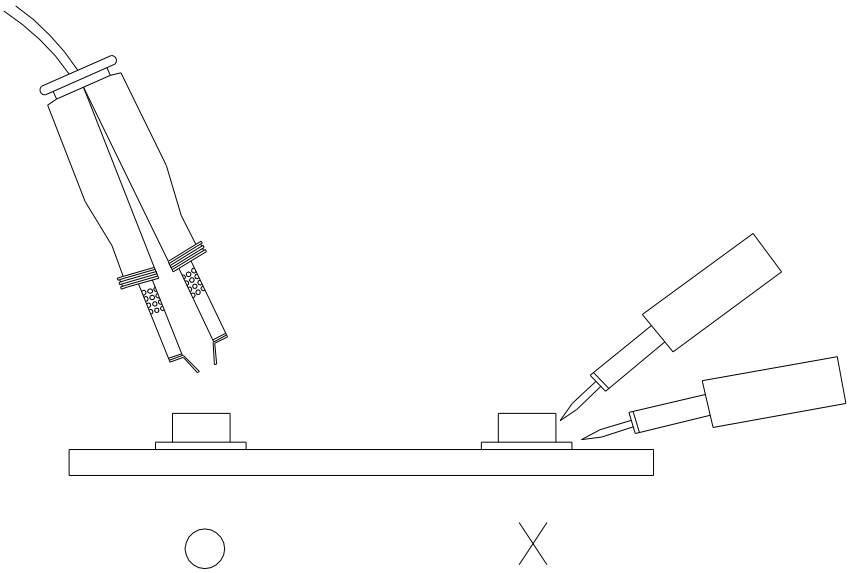
3.4 After soldering, do not warp the circuit board.

4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350℃ for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



EVERLIGHT ELECTRONICS CO., LTD.
Office: No 25, Lane 76, Sec 3, Chung Yang Rd,
Tucheng, Taipei 236, Taiwan, R.O.C
Tel: 886-2-2267-2000, 2267-9936
Fax: 886-2267-6244, 2267-6189, 2267-6306
http://www.everlight.com